

Title (en)  
PATTERN-FORMING METHODS

Title (de)  
BILDERZEUGUNGSVERFAHREN

Title (fr)  
PROCEDES DE FORMATION DE MOTIFS

Publication  
**EP 0953166 A2 19991103 (EN)**

Application  
**EP 98932356 A 19980702**

Priority

- GB 9801957 W 19980702
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- GB 9809346 A 19980501

Abstract (en)  
[origin: WO9901796A2] A method for producing a predetermined resist pattern on e.g. a lithographic printing plate, circuit board or mask comprises the imagewise exposure of a radiation sensitive diazide-containing coating (conventionally considered as a UV sensitive material), to non-UV radiation, such as direct heat radiation or infra-red radiation. A positive of the exposed image is revealed on development. Additionally, it has been found that a flood exposure to UV radiation after the imagewise exposure to the non-UV radiation means that a negative of the exposed image is revealed, on development.

IPC 1-7  
**G03F 7/023**

IPC 8 full level  
**G03F 7/039** (2006.01); **B41C 1/10** (2006.01); **B41M 5/36** (2006.01); **B41M 5/46** (2006.01); **C08F 12/24** (2006.01); **C08G 8/28** (2006.01); **C08L 25/18** (2006.01); **C08L 61/14** (2006.01); **G03F 7/022** (2006.01); **G03F 7/023** (2006.01); **G03F 7/20** (2006.01); **H05K 3/00** (2006.01)

CPC (source: EP US)  
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